

AF1333PUA-VB Datasheet

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^c	Q_g (Typ.)
- 20	0.080 at $V_{GS} = - 4.5$ V	- 3.1	4.3 nC
	0.100 at $V_{GS} = - 2.5$ V	- 2.3	

FEATURES

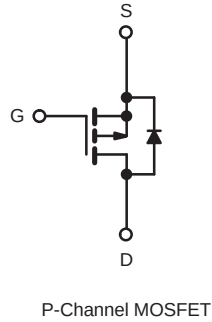
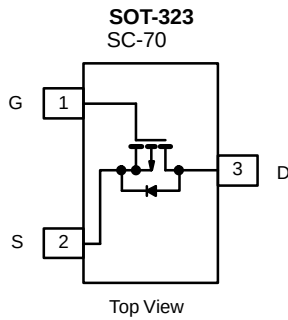
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load Switch
- DC/DC Converters



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	- 20	V
Gate-Source Voltage		V_{GS}	± 12	
Continuous Drain Current ($T_J = 150$ °C)	$T_C = 25$ °C	I_D	- 3.1	A
	$T_C = 70$ °C		- 2.1	
	$T_A = 25$ °C		- 1.4 ^{a, b}	
	$T_A = 70$ °C		- 1.1 ^{a, b}	
Pulsed Drain Current		I_{DM}	- 6	
Continuous Source-Drain Diode Current	$T_C = 25$ °C	I_S	- 0.4	W
	$T_A = 25$ °C		- 0.3	
Maximum Power Dissipation	$T_C = 25$ °C	P_D	0.5	
	$T_C = 70$ °C		0.3	
	$T_A = 25$ °C		0.4 ^{a, b}	
	$T_A = 70$ °C		0.3 ^{a, b}	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 50 to 150	°C
Soldering Recommendations (Peak Temperature)			260	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. $t = 10$ s.

c. Based on $T_C = 25$ °C.

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, b}	$t \leq 10$ s	R_{thJA}	250	300	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	225	270	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. Maximum under steady state conditions is 360 °C/W.

SPECIFICATIONS ($T_J = 25$ °C, unless otherwise noted)

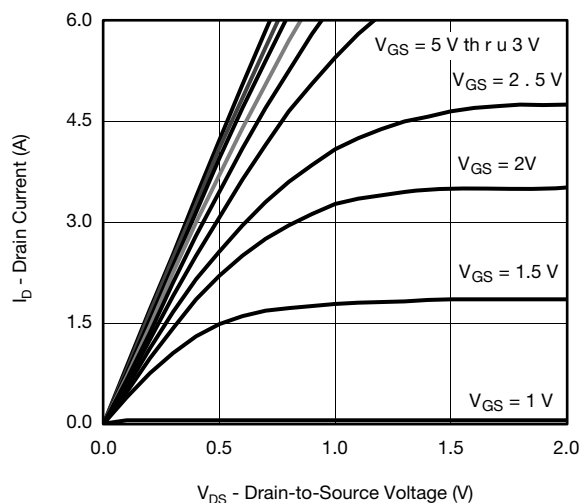
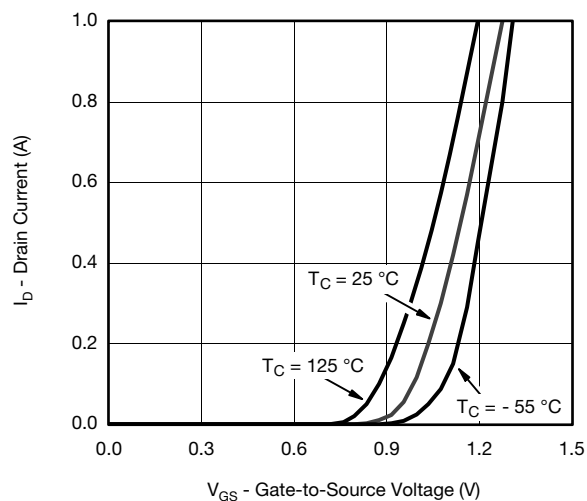
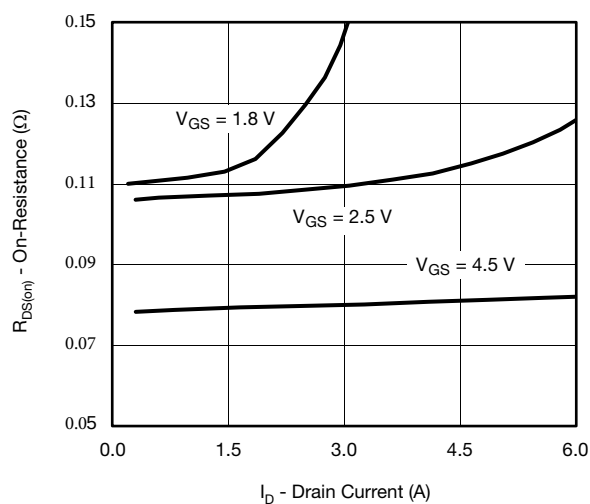
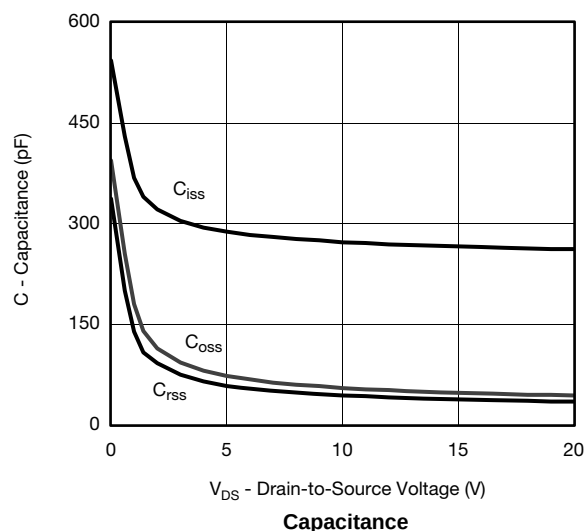
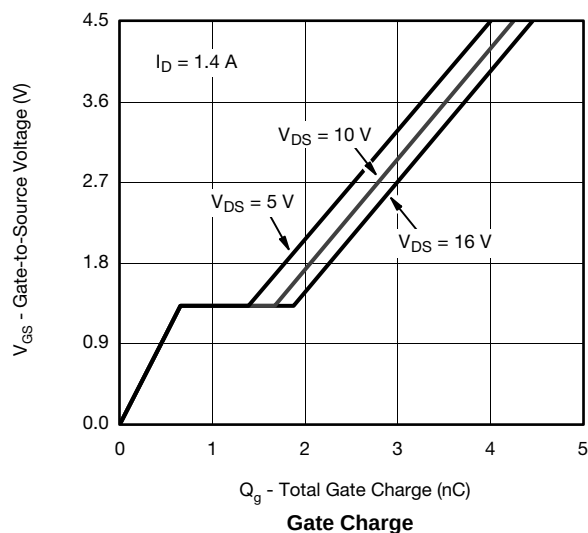
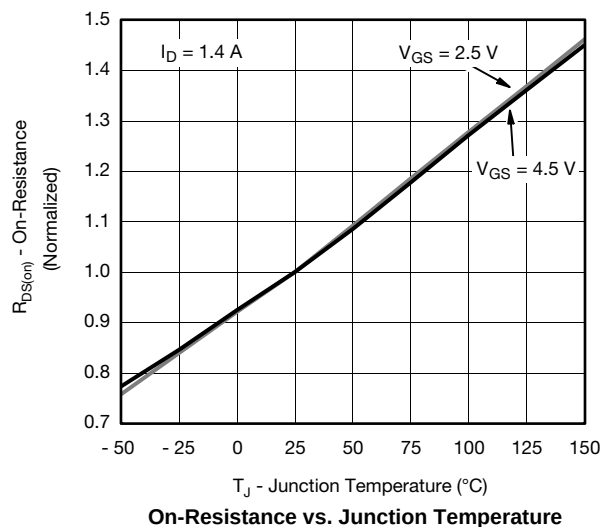
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		- 14		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			2.4		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.45		- 1.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 5 V, V _{GS} = - 4.5 V	- 2			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 1.4 A		0.080		Ω
		V _{GS} = - 2.5 V, I _D = - 1.2 A		0.100		
		V _{GS} = - 1.8 V, I _D = - 0.3 A		0.140		
Forward Transconductance ^a	g _{fs}	V _{DS} = - 5 V, I _D = - 1.4 A		5		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		272		pF
Output Capacitance	C _{oss}			55		
Reverse Transfer Capacitance	C _{rss}			44		
Total Gate Charge	Q _g	V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 1.4 A		4.3	6.5	nC
		V _{DS} = - 10 V, V _{GS} = - 2.5 V, I _D = - 1.4 A		2.7	4.1	
Gate-Source Charge	Q _{gs}			0.7		
Gate-Drain Charge	Q _{gd}			1.0		
Gate Resistance	R _g	f = 1 MHz	1.4	7	14	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 9.1 Ω I _D ≅ - 1.1 A, V _{GEN} = - 4.5 V, R _g = 1 Ω		12	20	ns
Rise Time	t _r			20	30	
Turn-Off DelayTime	t _{d(off)}			23	35	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 9.1 Ω I _D ≅ - 1.1 A, V _{GEN} = - 8 V, R _g = 1 Ω		5	10	
Rise Time	t _r			10	20	
Turn-Off DelayTime	t _{d(off)}			18	27	
Fall Time	t _f			7	14	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.4	A
Pulse Diode Forward Current ^a	I _{SM}				- 6	
Body Diode Voltage	V _{SD}	I _F = - 0.7 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = - 0.7 A, dI/dt = 100 A/μs, T _J = 25 °C		18	27	ns
Body Diode Reverse Recovery Charge	Q _{rr}			7	14	nC
Reverse Recovery Fall Time	t _a			7		ns
Reverse Recovery Rise Time	t _b			11		

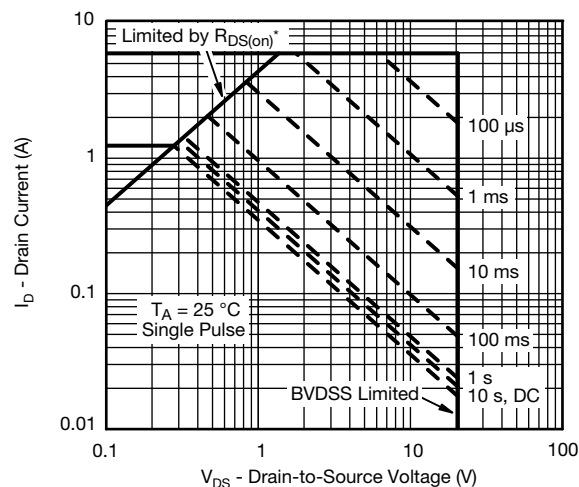
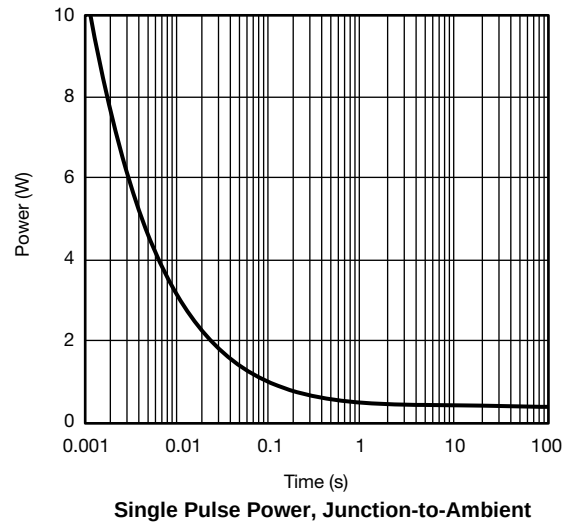
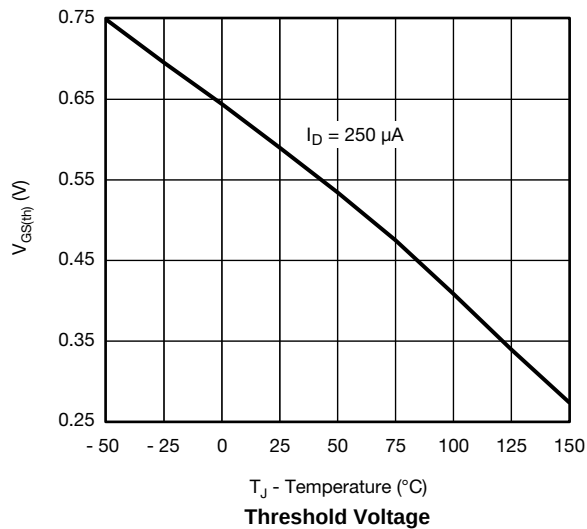
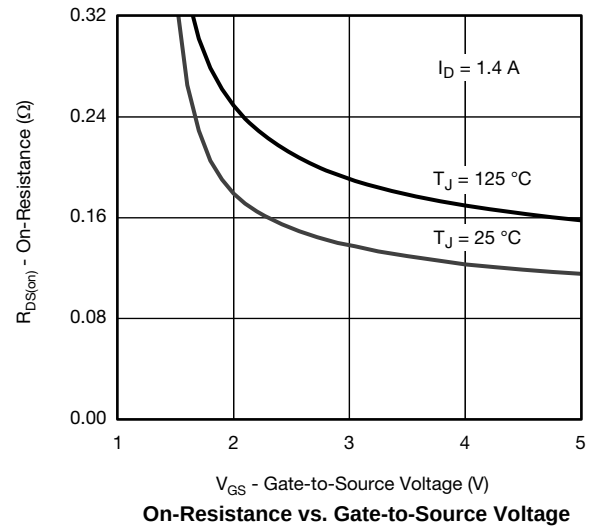
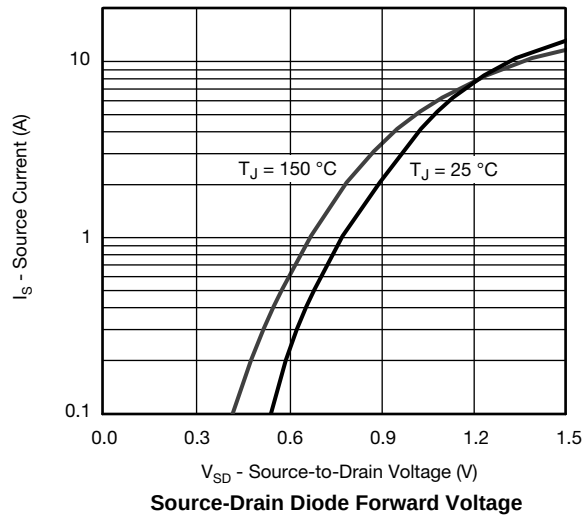
Notes:

a. Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %.

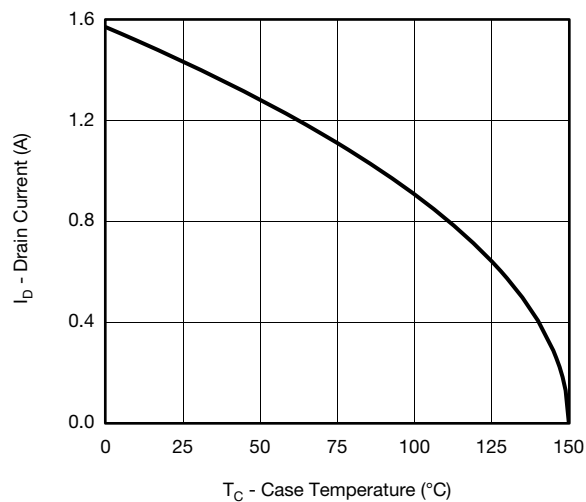
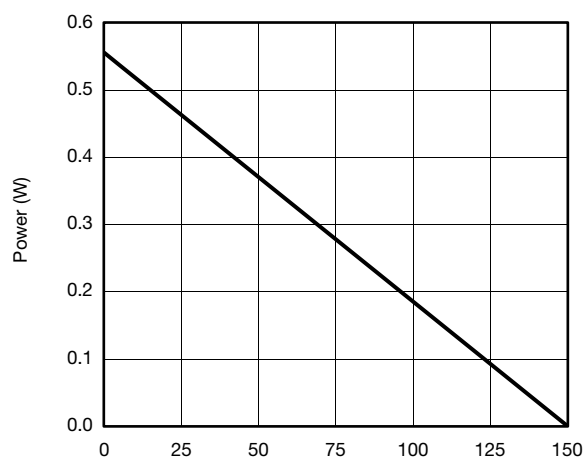
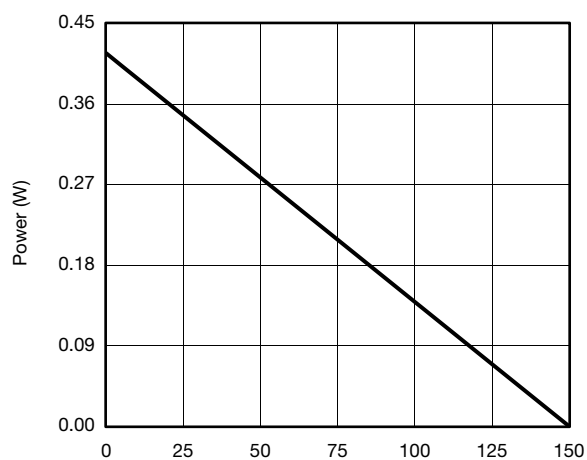
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature

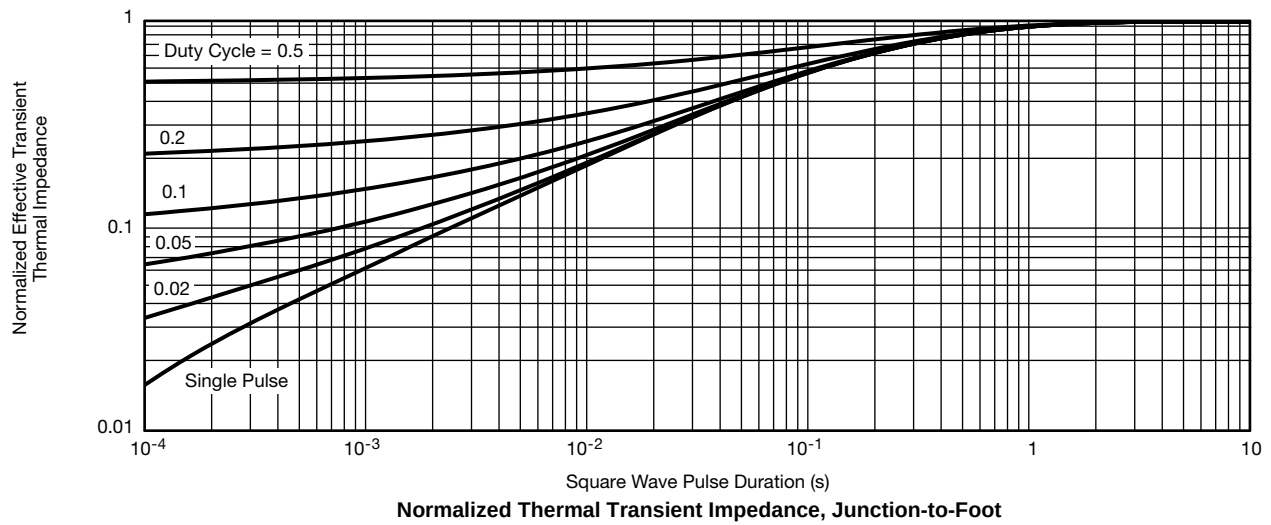
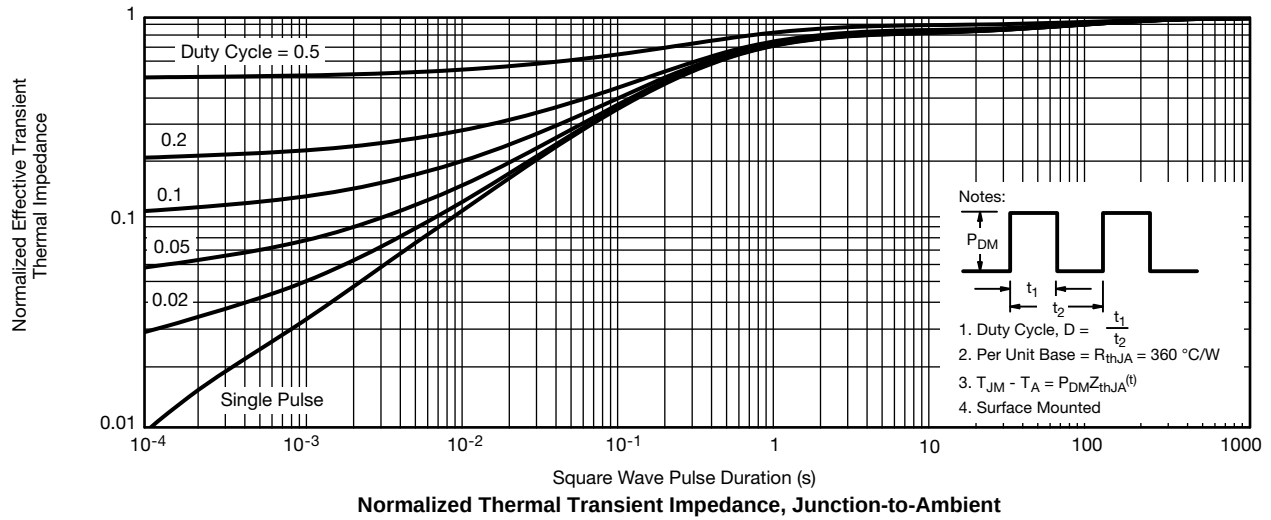
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified
Safe Operating Area, Junction-to-Ambient

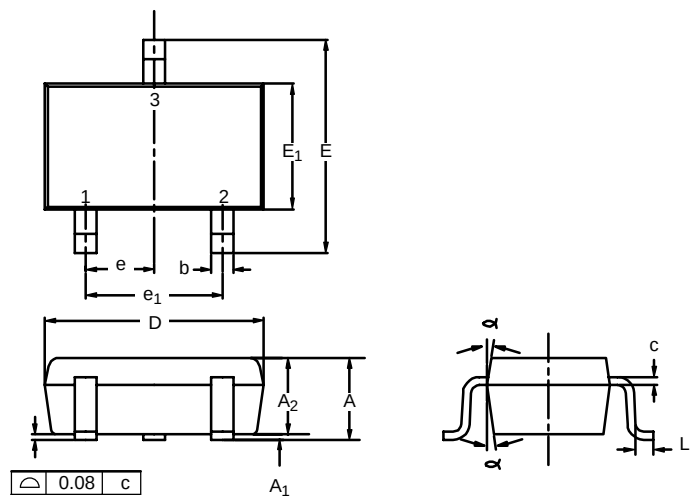
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating*

Power, Junction-to-Case

Power, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

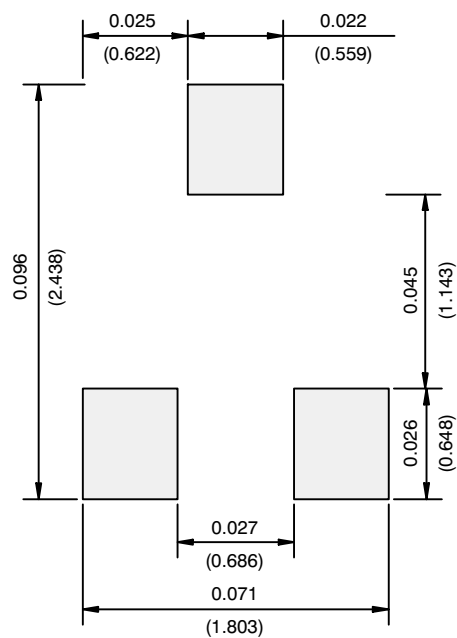


SC-70: 3-LEADS



Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	0.90	—	1.10	0.035	—	0.043
A ₁	—	—	0.10	—	—	0.004
A ₂	0.80	—	1.00	0.031	—	0.039
b	0.25	—	0.40	0.010	—	0.016
c	0.10	—	0.25	0.004	—	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
E	1.80	2.10	2.40	0.071	0.083	0.094
E ₁	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65BSC			0.026BSC		
e ₁	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
α	7°Nom			7°Nom		
ECN: S-03946—Rev. C, 09-Jul-01						
DWG: 5549						

RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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